



2 CHANNEL LOW CAPACITANCE CSP TVS DIODE ARRAY

Product Summary

| V _{BR (Min)} | I _{PP (Max)} | C _{I/O} (Max) |
|-----------------------|-----------------------|------------------------|
| 6V | 5.5A | 0.75pF |

Description

This new generation TVS is designed to protect sensitive electronics from the damage due to ESD. The combination of small size and high ESD surge capability makes it ideal for use in portable applications such as cellular phones, digital cameras, and MP3 players.

Applications

Typically used at high-speed ports such as USB 2.0, IEEE1394 (FireWire®, iLink), Serial ATA, DVI™, HDMI™, PCI™.

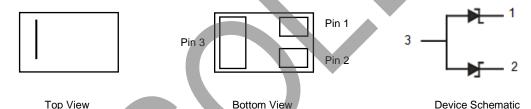
Features

- Clamping Voltage: 9V at 10A 100ns, TLP 9.4V at 5.5A 8µs/20µs
- IEC 61000-4-2 (ESD): Air ±16kV, Contact ±16kV
- IEC 61000-4-5 (Lightning): 5.5A (8/20µs)
- 2 Channels of ESD Protection
- Low Channel Input Capacitance of 0.75pF Max
- TLP Dynamic Resistance: 0.25Ω
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: X3-DSN1006-3
- Case Material: Chip Scale Package
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method
- Weight: 0.001 grams (Approximate)

X3-DSN1006-3 (Type B)



Ordering Information (Note 4).

| Product | Compliance | Marking | Reel Size (inches) | Tape Width (mm) | Quantity per Reel |
|------------------|------------|---------|--------------------|-----------------|--------------------|
| DT1240-02LP10-7B | Standard | MJ | 7 | 8 | 10,000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



Top View Bar Denotes Pin 1 and Pin 2 MJ = Product Type Marking Code

DT1240-02LP10
Document number: DS38730 Rev. 4 - 4



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | Conditions |
|---|--------------------------|-------------|------|---------------------------------|
| Peak Pulse Current, per IEC 61000-4-5 | IPP | 5.5 | Α | I/O to V _{SS} , 8/20µs |
| Peak Pulse Power, per IEC 61000-4-5 | P _{PP} | 55 | W | I/O to V _{SS} , 8/20µs |
| ESD Protection – Contact Discharge, per IEC 61000-4-2 | V _{ESD_CONTACT} | ±16 | kV | I/O to V _{SS} |
| ESD Protection – Air Discharge, per IEC 61000-4-2 | V _{ESD_AIR} | ±16 | kV | I/O to V _{SS} |
| Operating Temperature | T _{OP} | -55 to +85 | °C | _ |
| Storage Temperature | T _{STG} | -55 to +150 | °C | _ |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|--|----------------|-------|------|
| Power Dissipation Typical (Note 5) | P _D | 500 | mW |
| Thermal Resistance, Junction to Ambient Typical (Note 5) | $R_{	hetaJA}$ | 250 | °C/W |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Conditions |
|-----------------------------------|--------------------|------|-------|---------------|------|---|
| Reverse Working Voltage | V_{RWM} | _ | _ | 5.5 | V | $I_R=1$ mA, , I/O to V_{SS} |
| Reverse Current | I _R | _ | 1 | 0.5 | μA | $V_R = 5.5V$, I/O to V_{SS} |
| Reverse Breakdown Voltage | V_{BR} | 6 | | | V | $I_R = 1 \text{mA}$, I/O to V_{SS} |
| Forward Clamping Voltage | V_{F} | -1.0 | -0.85 | _ | V | $I_F = -15 \text{mA}$, I/O to V_{SS} |
| Reverse Clamping Voltage (Note 6) | Vc | _ | 9.4 | 11 | V | $I_{PP} = 5.5A$, I/O to V _{SS} , 8/20 μ s |
| ESD Clamping Voltage | V _{ESD} | | 9 | | V | TLP, 10A, tp = 100ns, I/O to V _{SS} |
| Dynamic Reverse Resistance | R _{DIF-R} | _ | 0.25 | | Ω | TLP, 10A, tp = 100ns, I/O to V_{SS} |
| Dynamic Forward Resistance | R _{DIF-F} | _ | 0.25 | $\overline{}$ | Ω | TLP, 10A, tp = 100ns, V _{SS} to I/O |
| Channel Input Capacitance | C _{I/O} | _ | 4 | 0.75 | pF | $V_{I/O} = 2.5V$, $V_{SS} = 0V$, $f = 1MHz$ |
| Delta C _{I/O} | CI/OMAX-CI/OMIN | _ | 0.04 | _ | pF | C _{I/OMAX} -C _{I/OMIN} |

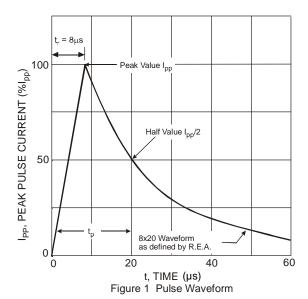
Notes:

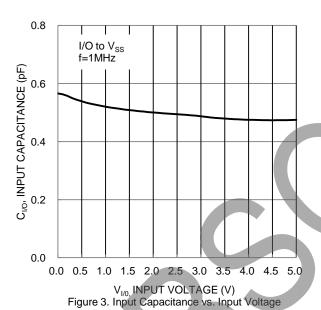
- 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at http://www.diodes.com/package-outlines.html.

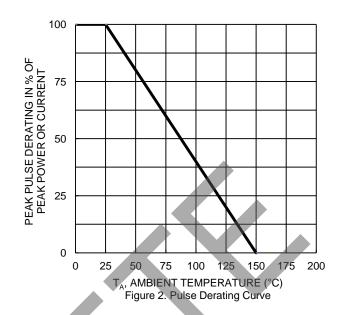
 6. Clamping voltage value is based on an 8x20µs peak pulse current (I_{PP}) waveform.

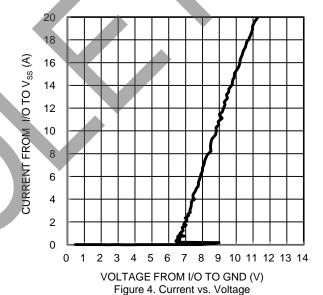










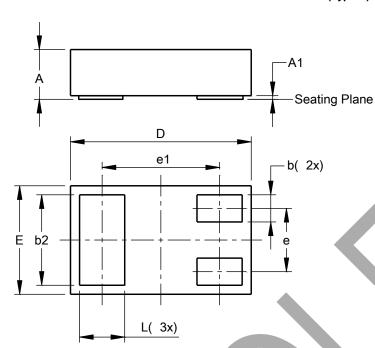




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-DSN1006-3 (Type B)



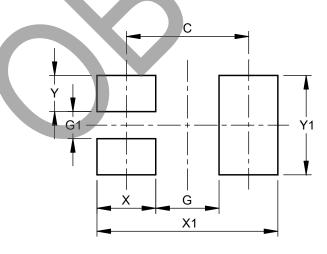
| X3-DSN1006-3 | | | | | | |
|----------------------|----------|-------|-------|--|--|--|
| | (Type B) | | | | | |
| Dim | Min | Max | Тур | | | |
| Α | 0.250 | 0.300 | 0.275 | | | |
| A1 | 0.00 | 0.02 | 0.01 | | | |
| b | 0.130 | 0.170 | 0.150 | | | |
| b2 | 0.480 | 0.520 | 0.500 | | | |
| D | 0.975 | 1.025 | 1.00 | | | |
| E | 0.575 | 0.625 | 0.600 | | | |
| е | | | 0.350 | | | |
| e1 | | | 0.650 | | | |
| L | 0.230 | 0.270 | 0.250 | | | |
| All Dimensions in mm | | | | | | |

Note 7: Device side walls are electrically active bare silicon. Avoid contact of solder or flux on the side walls during the PCB assembly process.

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-DSN1006-3 (Type B)



| Dimensions | Value (in mm) | | |
|------------|------------------|--|--|
| C | 0.70 | | |
| G | 0.30 | | |
| G1 | 0.20 | | |
| X | 0.40 | | |
| X1 | 1.10 | | |
| Y | 0.25 | | |
| Y1 | 0.70 | | |



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